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US2015267313A1 ELECTRODEPOSITED COPPER FOIL

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Abstract

An electrodeposited copper foil having a texture coefficient of a plane (200) from 50 to 80%, based on the sum of the texture coefficients of a plane (111), the plane (200), a plane (220) and a plane (200) of the electrodeposited copper foil is provided. The electrodeposited copper foil is particularly suitable for use in the applications in printed circuit boards and lithium ion secondary batteries.